

Inventor: Shen Buswell et al
Title: Methods and systems for a forming slots in a semiconductor substrate containing . . .

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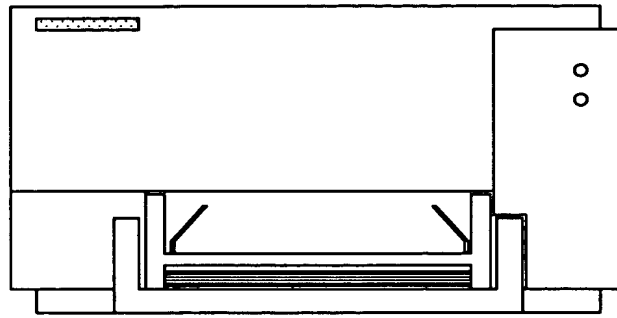


Fig.1

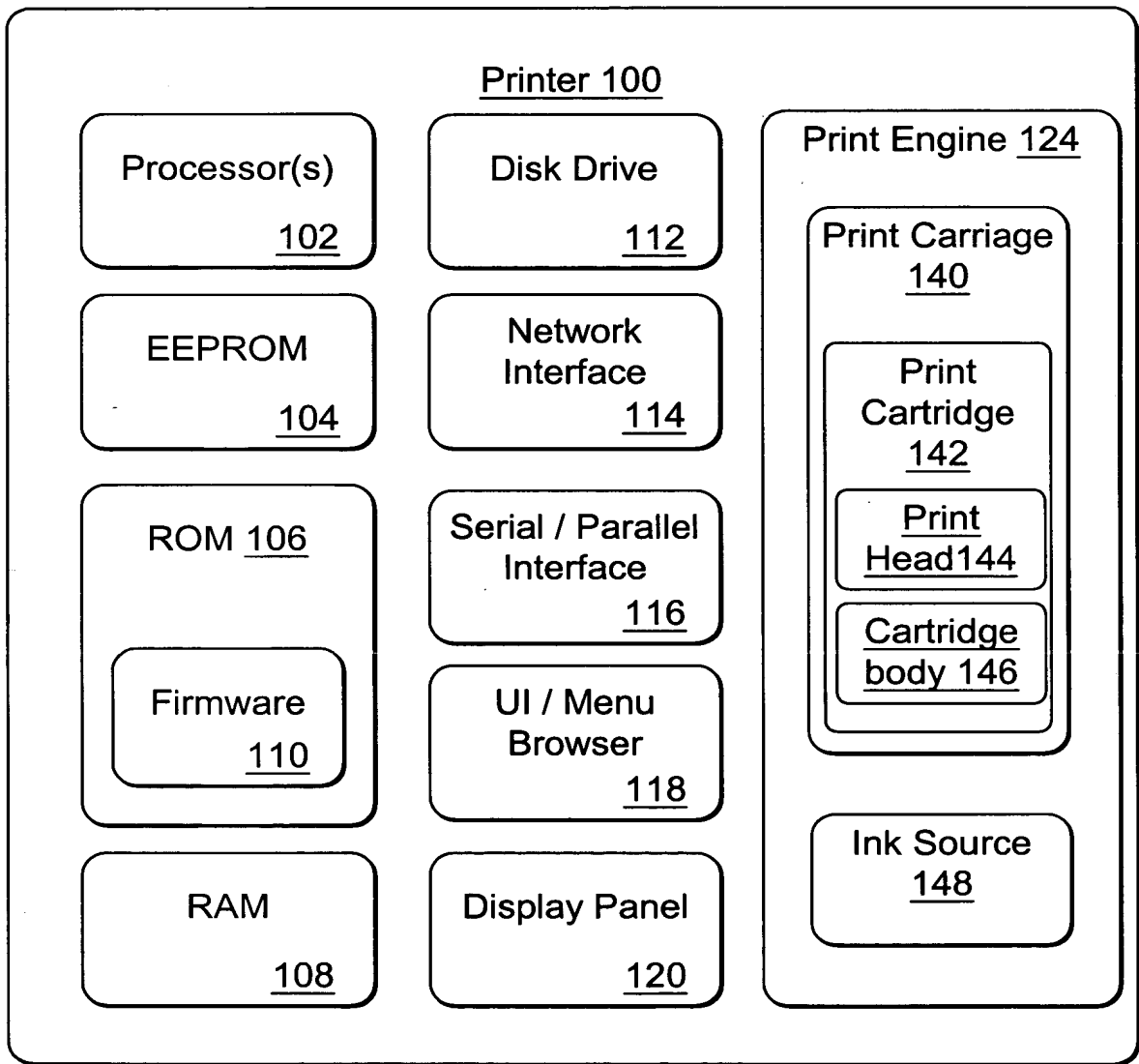


Fig. 2

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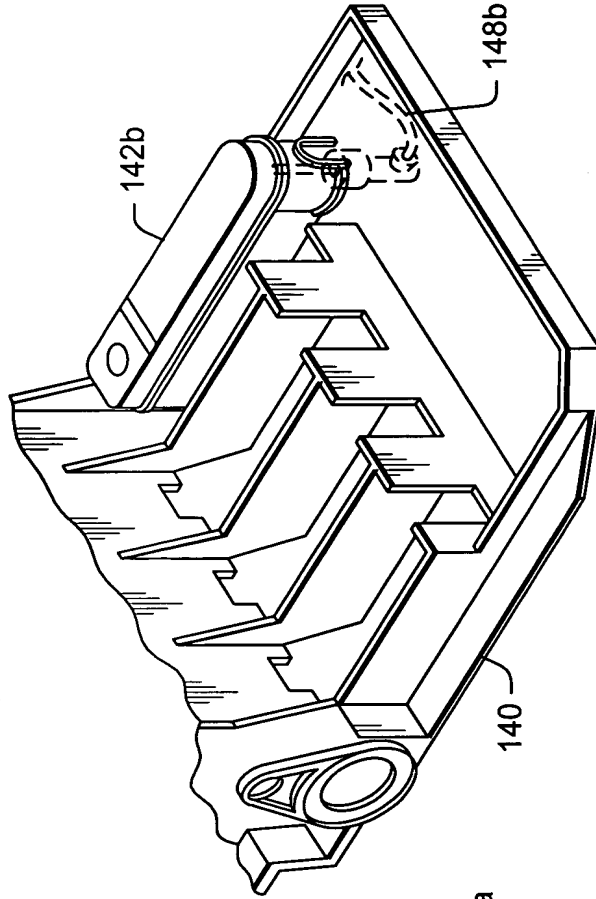


FIG. 3

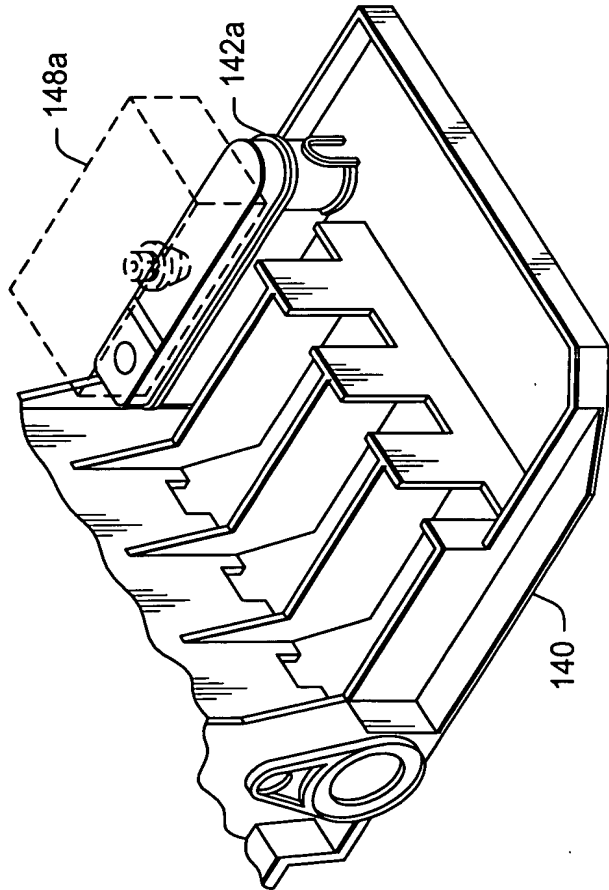


FIG. 4

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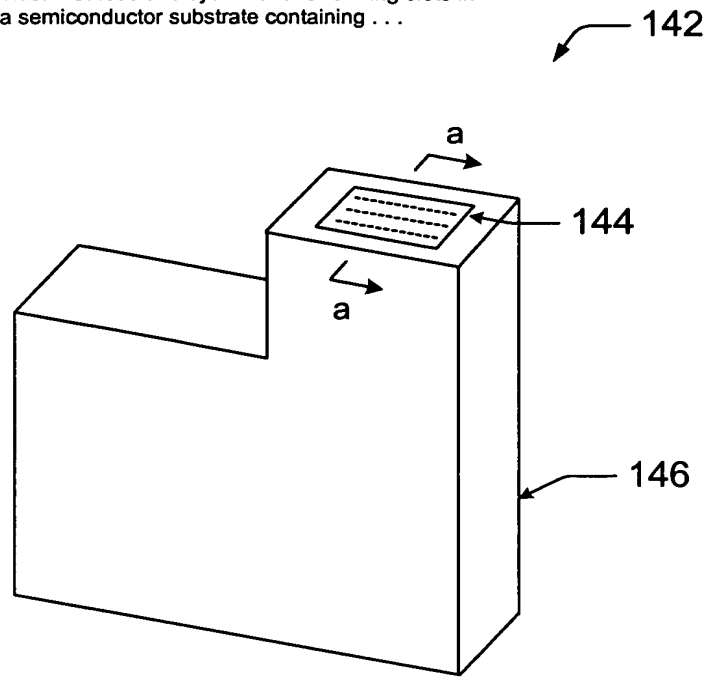


Fig. 5

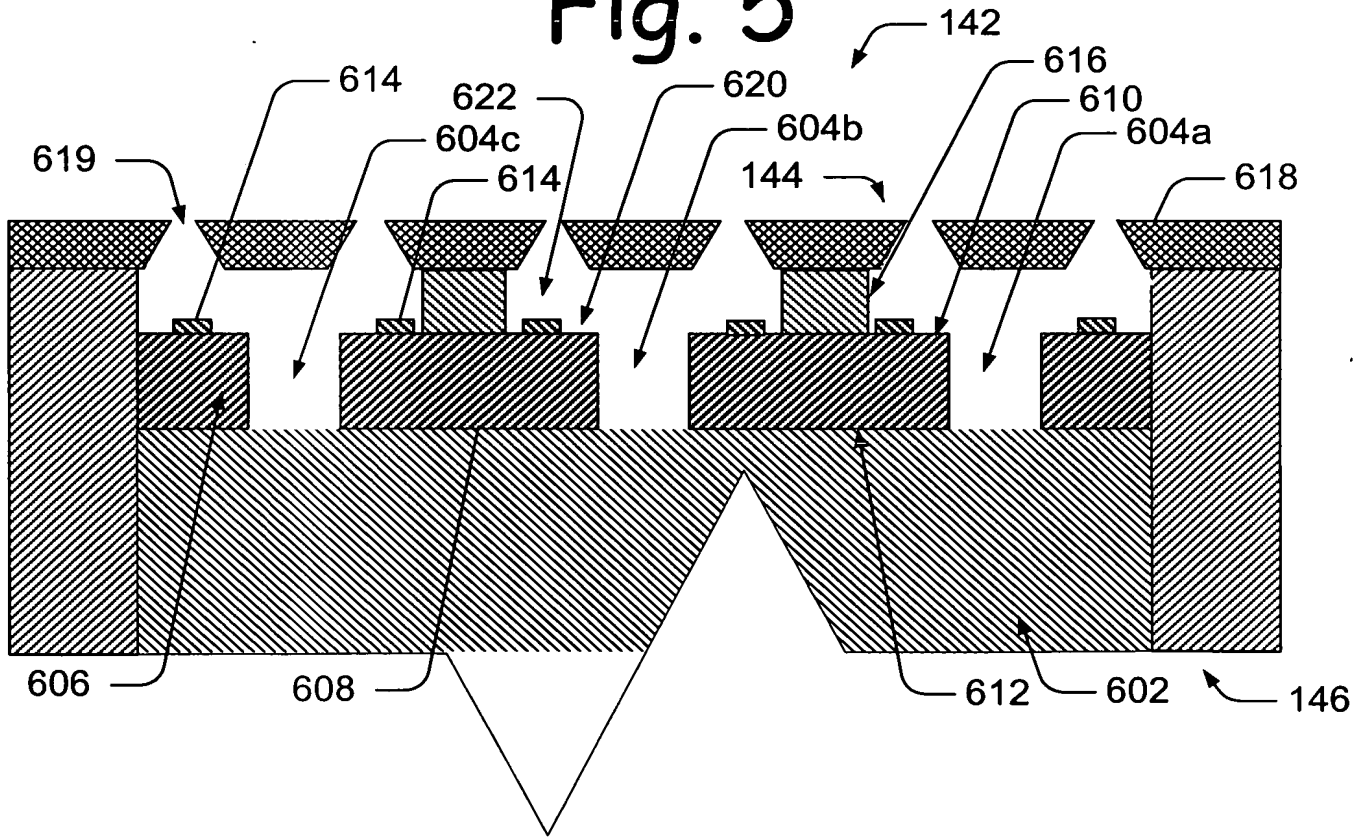


Fig. 6

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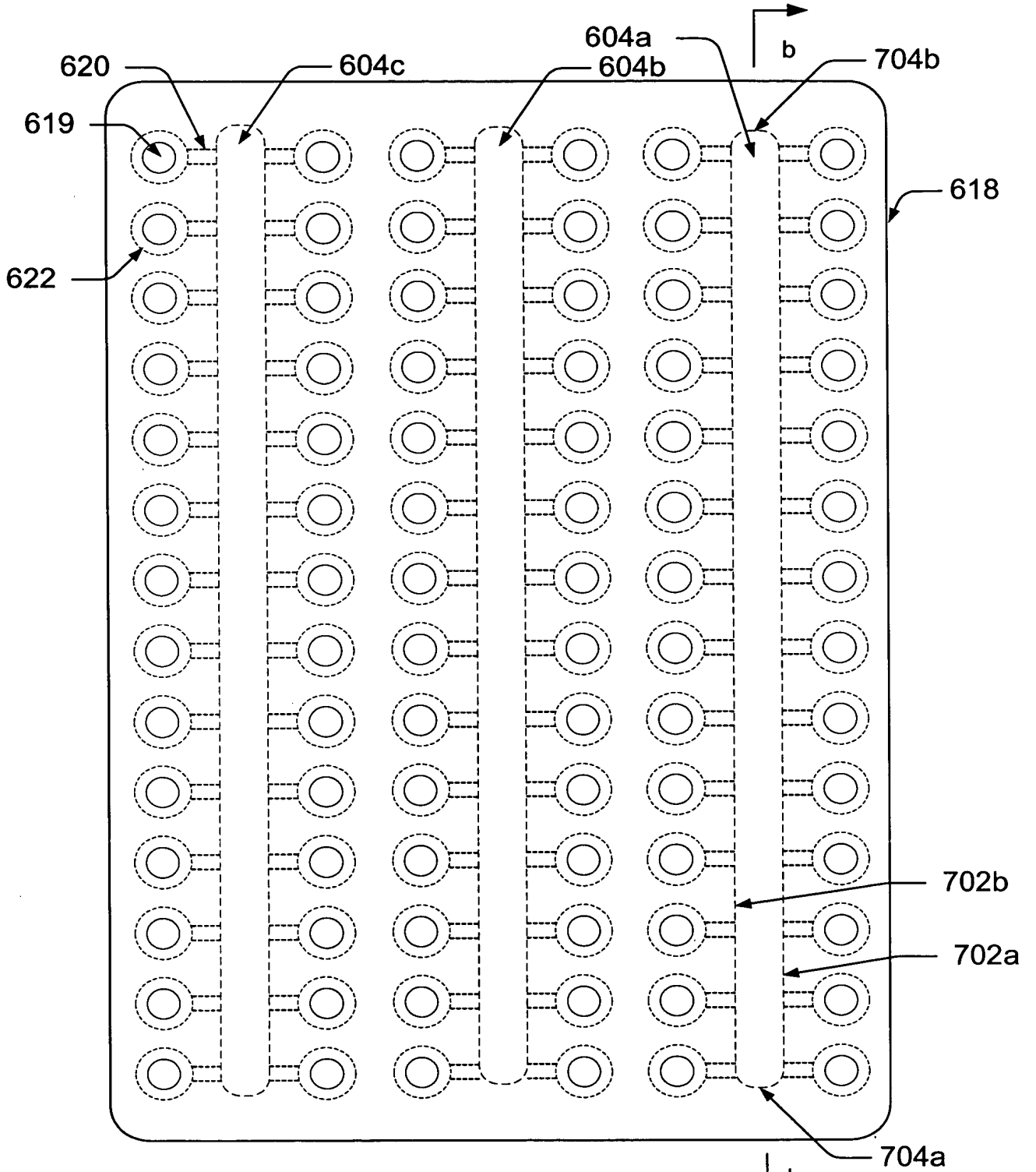


Fig. 7

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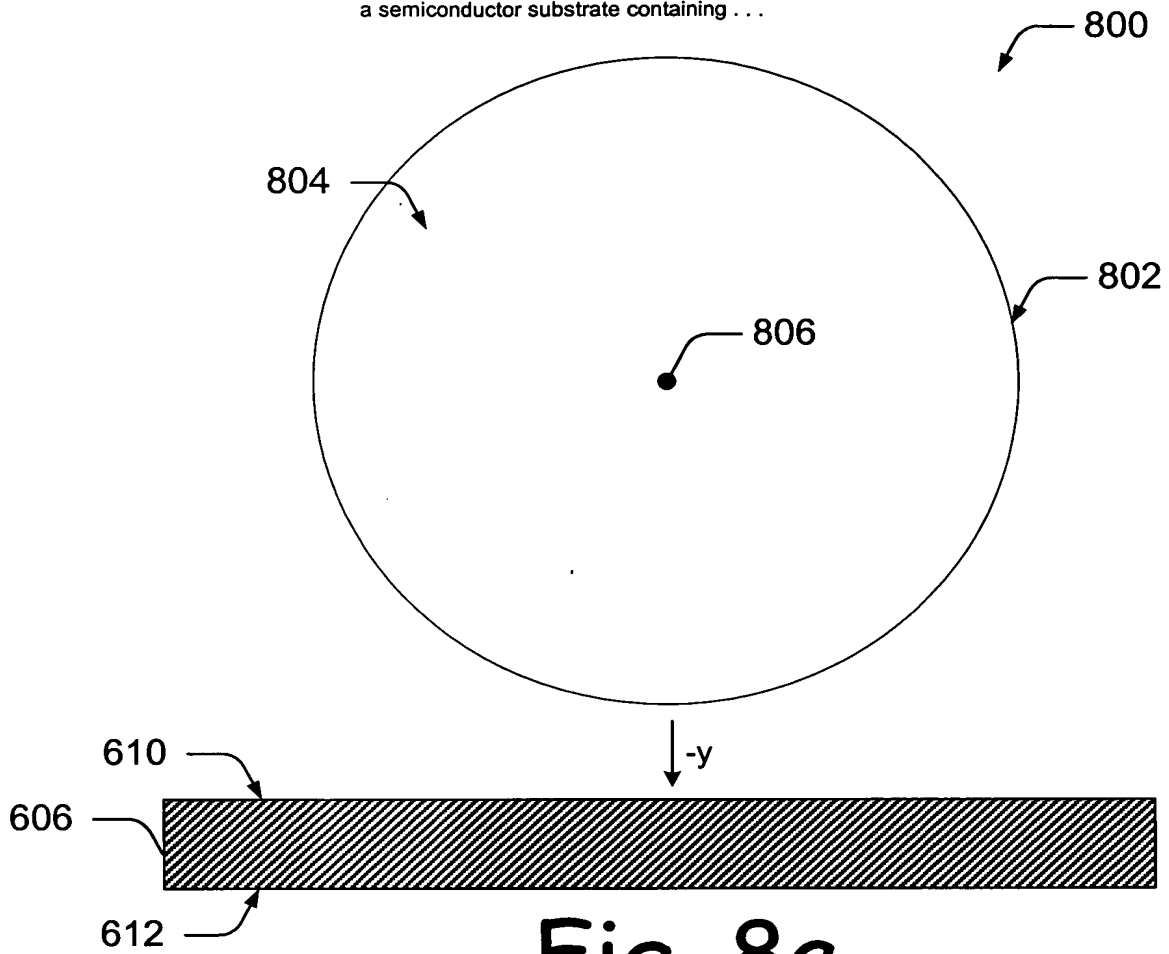


Fig. 8a

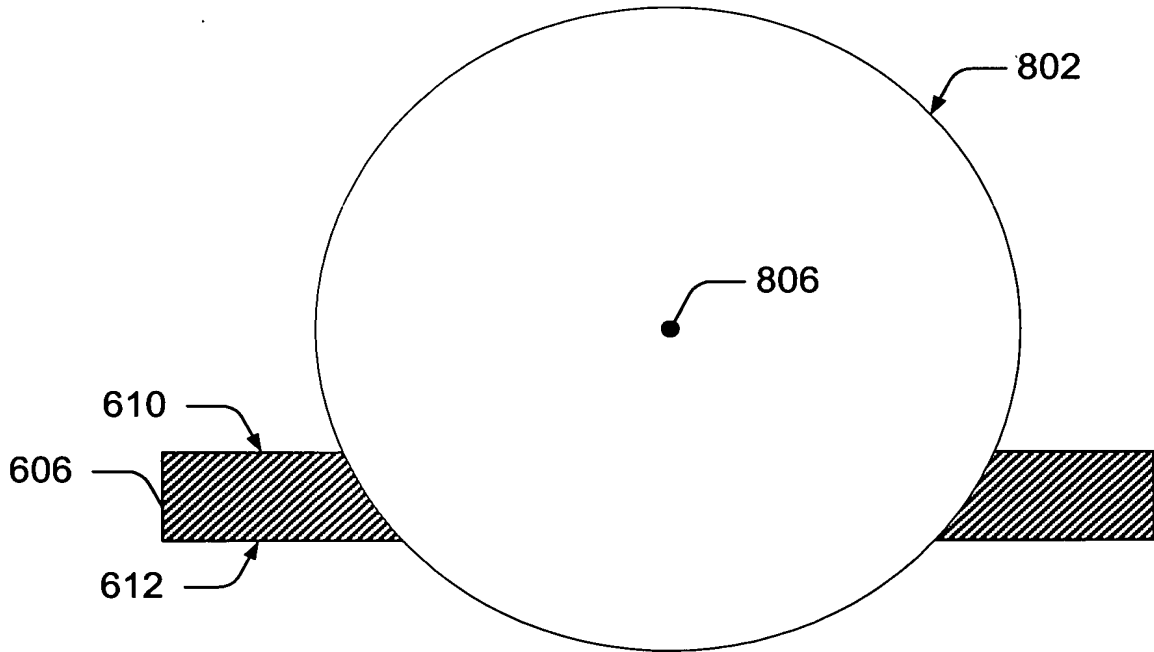


Fig. 8b

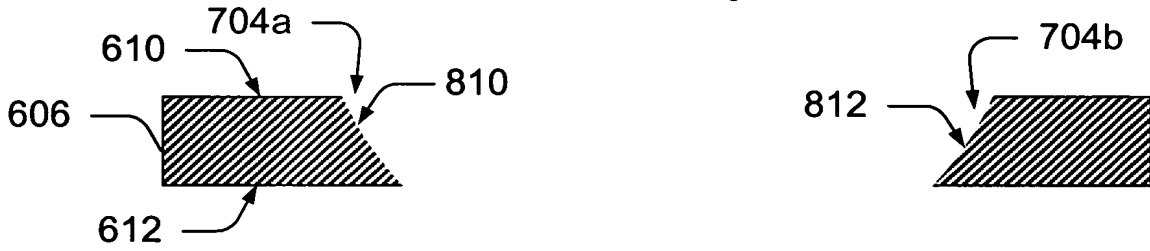


Fig. 8c

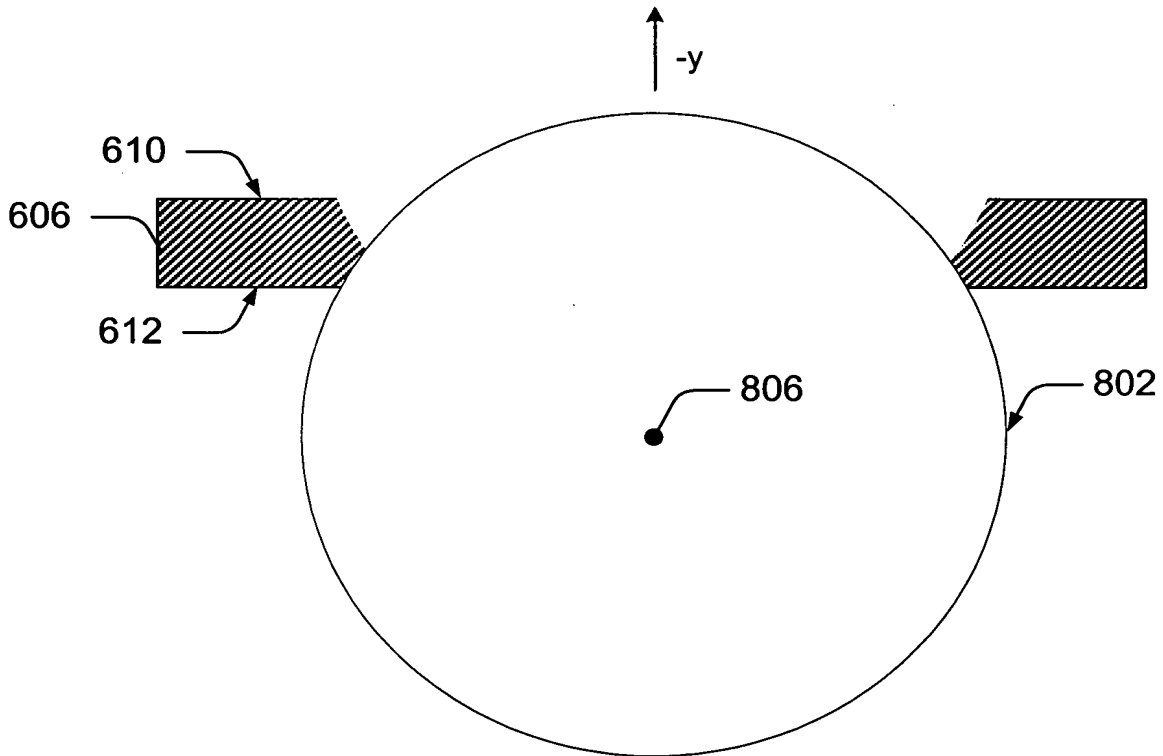


Fig. 8d

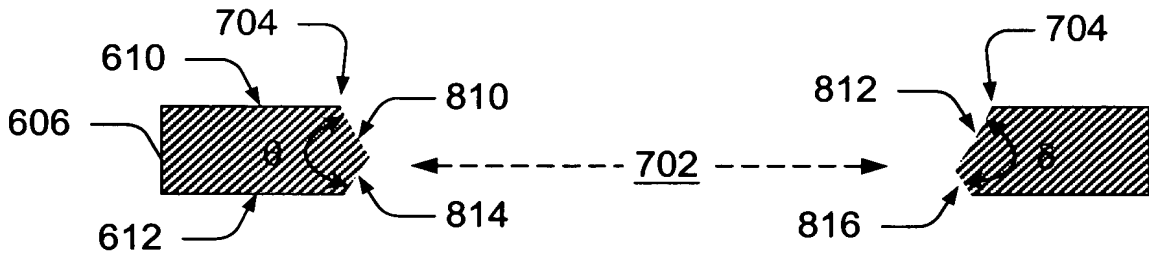


Fig. 8e

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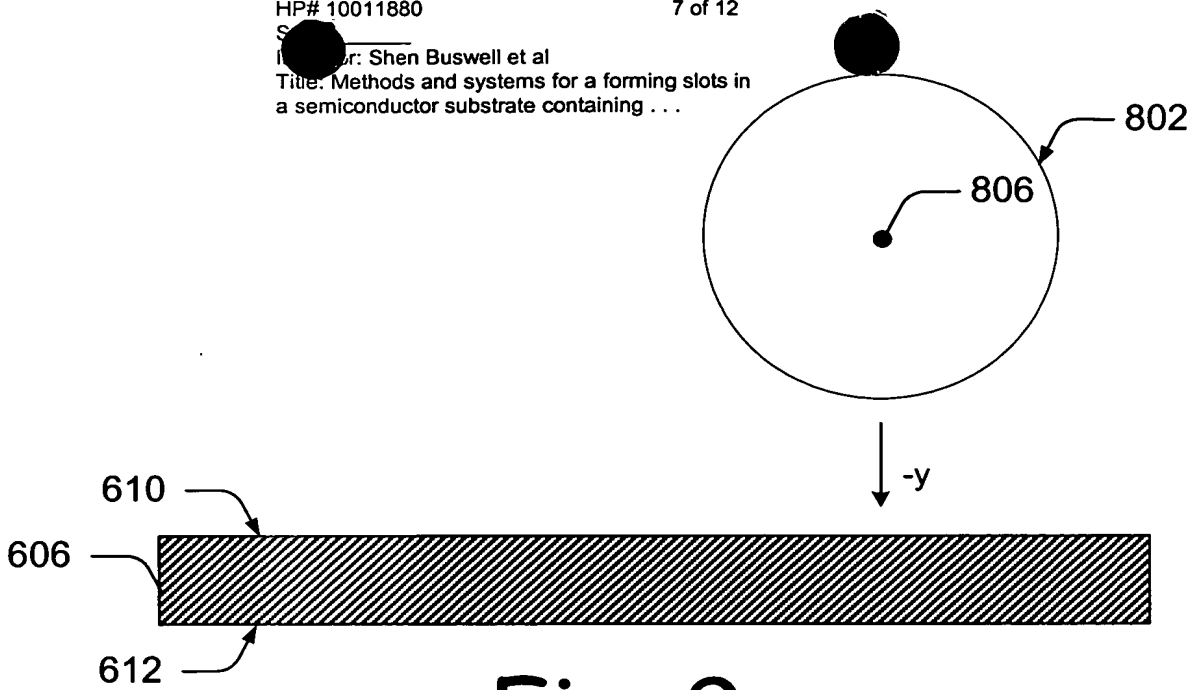


Fig. 9a

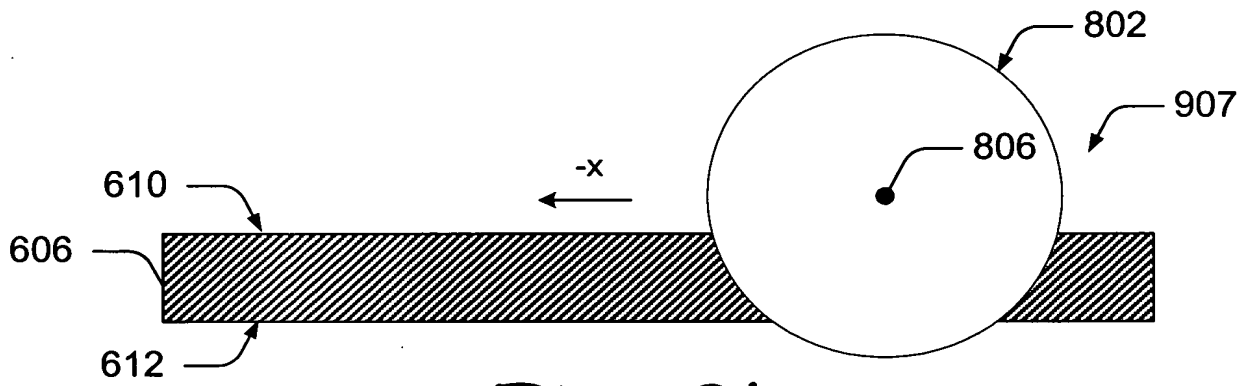


Fig. 9b

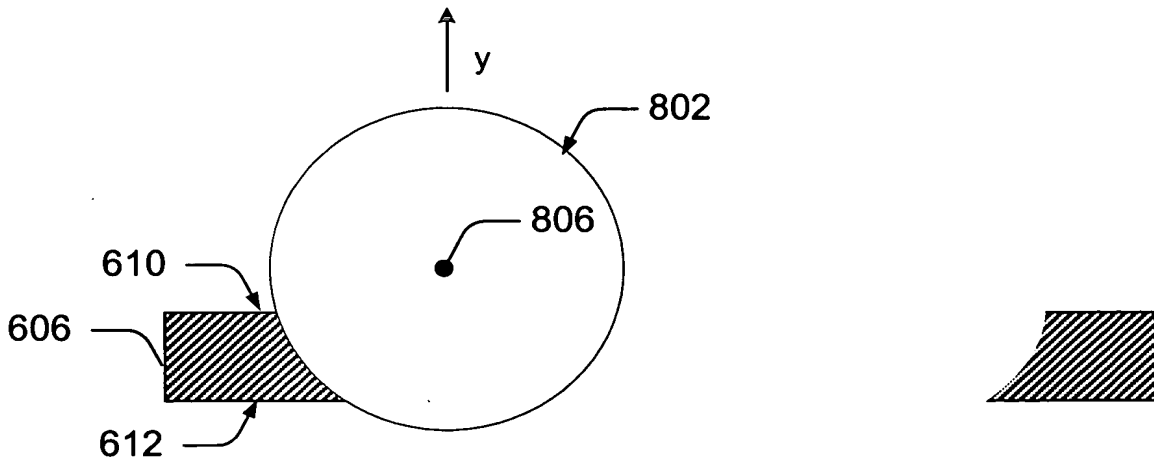


Fig. 9c

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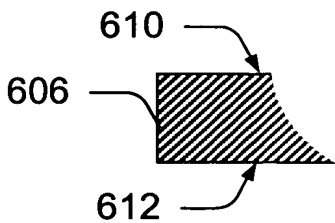


Fig. 9d

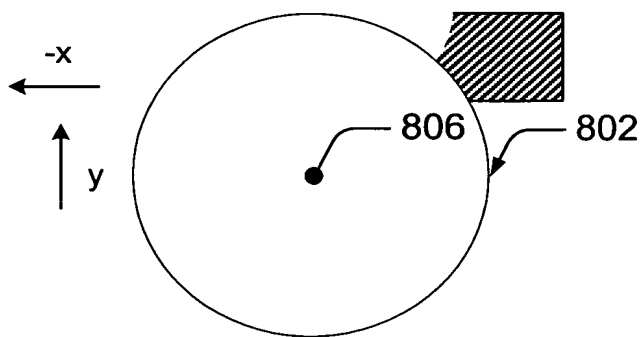
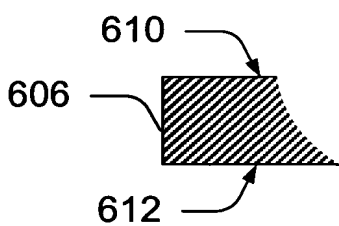


Fig. 9e

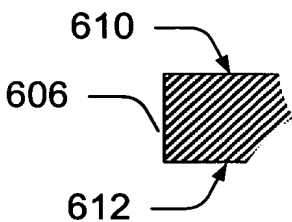


Fig. 9f

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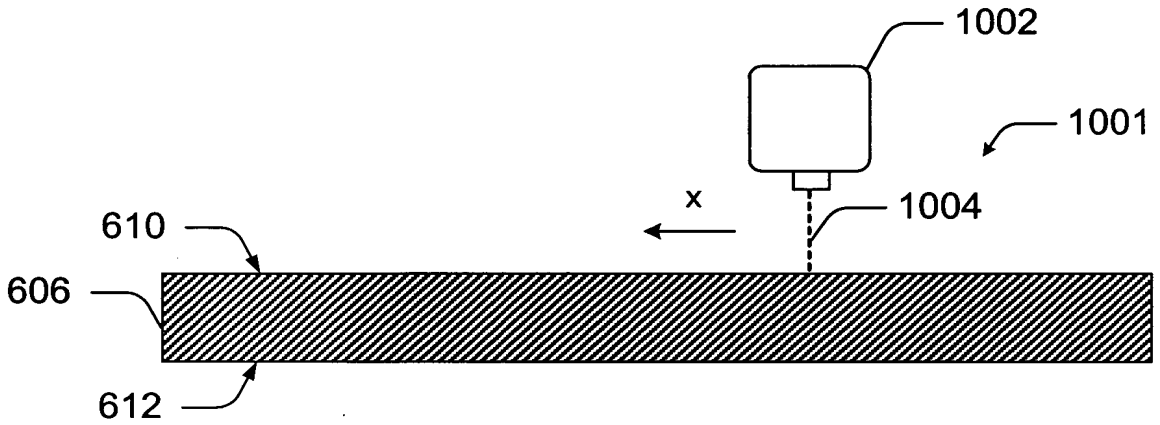


Fig. 10a

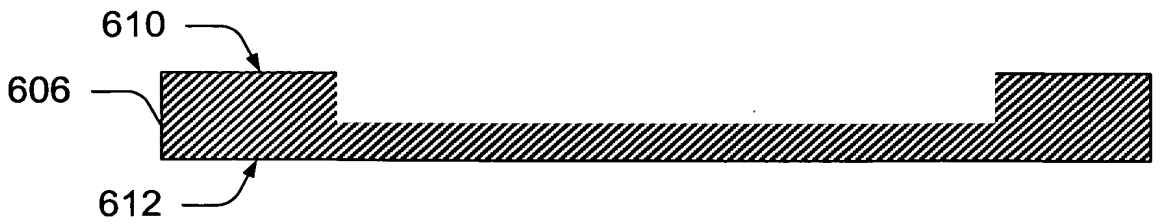


Fig. 10b

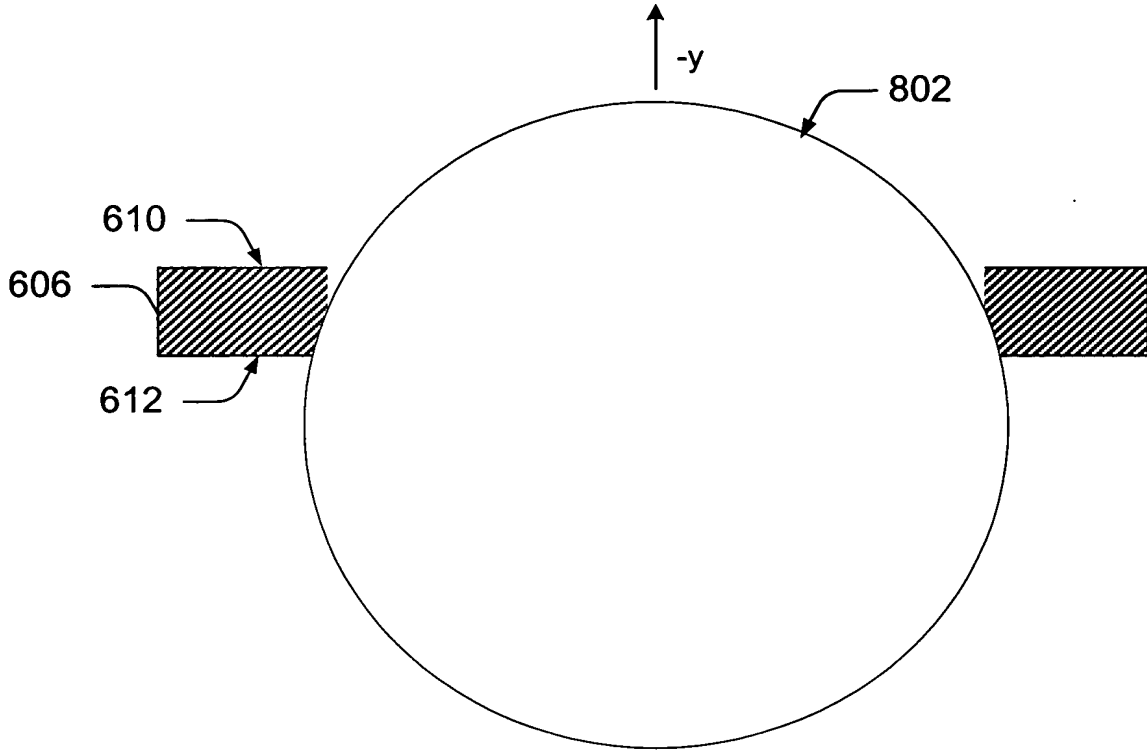


Fig. 10c



Fig. 10d

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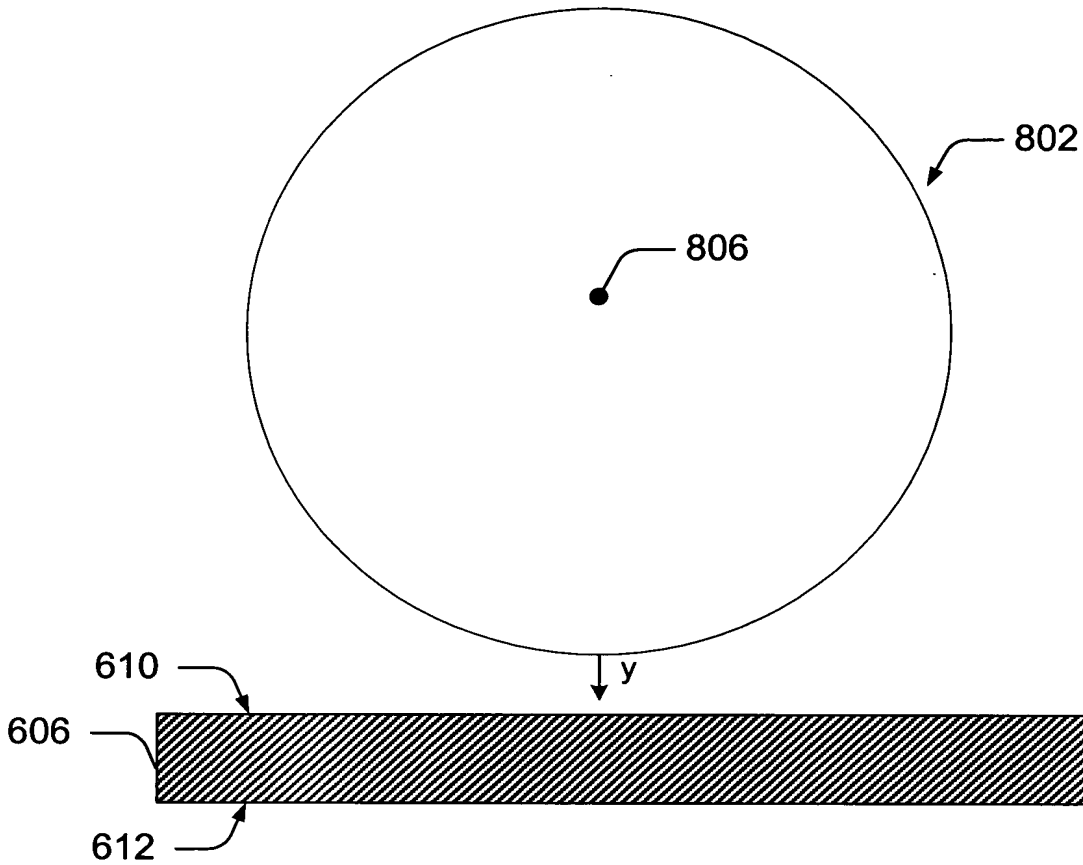


Fig. 11a

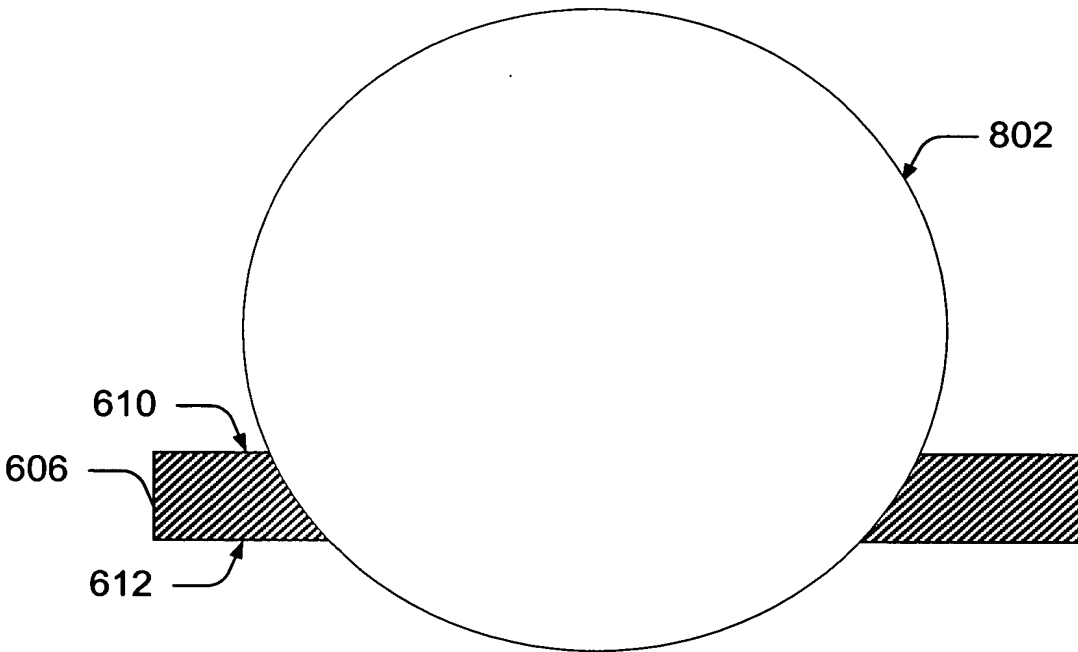


Fig. 11b

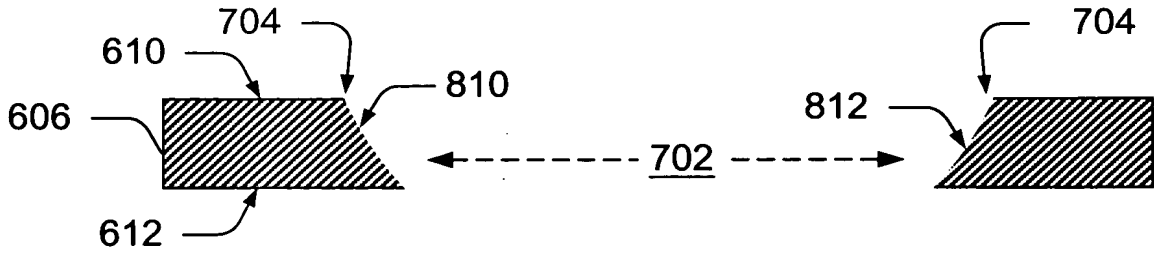


Fig. 11c

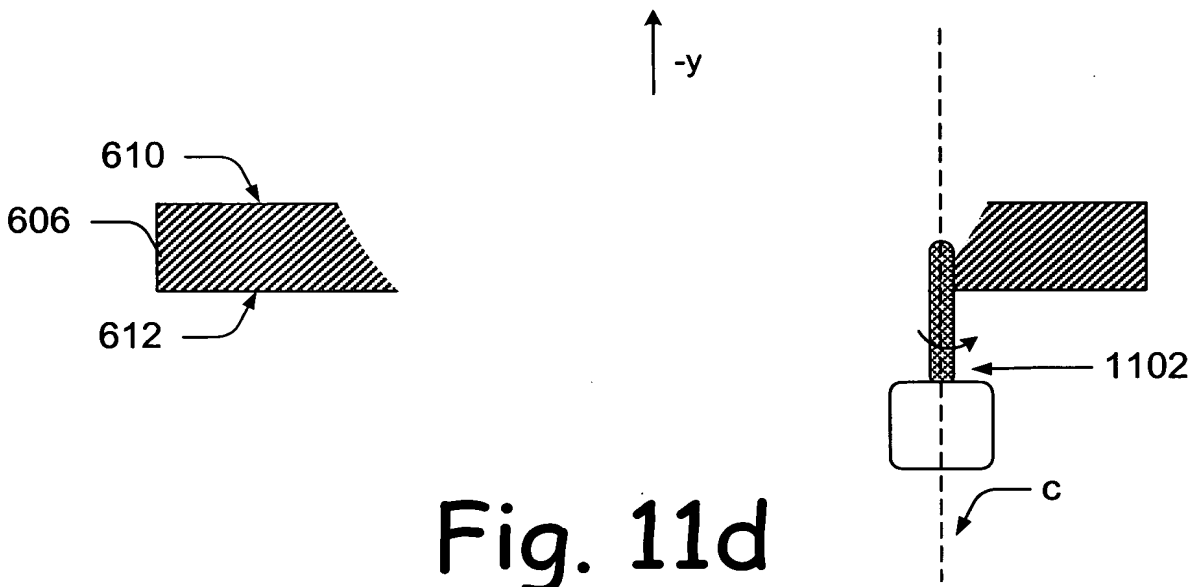


Fig. 11d

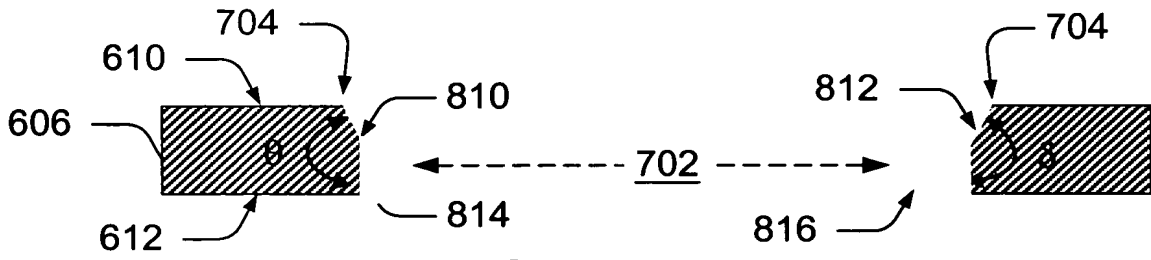


Fig. 11e

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